

BOARD-TO-BOARD HEADERS & RECEPTACLES



✓ Active

TE CONNECTIVITY (TE)

FB-5R,ASY,120,SIG,REC,SL,2.73

Z-PACK | Future Bus+

5223004-4

TE Internal Number: 5223004-4

EU RoHS Compliant EU ELV Compliant

Connector Style Receptacle

Number of Positions 120

Centerline (Pitch) 2 mm [.079 in]

Packaging Method Tube

Contact Mating Area Plating Material Gold



PRODUCT DRAWING

English



★ 3D PDF

DOCUMENTATION

Product Drawings

ASSEMBLY, RECEPTACLE, SIGNAL, RIGHT ANGLE, Z-PACK 2mm FB, 5 ROW, SOLDER LEAD

PDF

English

CAD Files

3D PDF

PDF

English

Customer View Model

2D_DXF.ZIP

English

3D_IGS.ZIP English
Customer View Model 3D_STP.ZIP English
Product Specifications
Application Specification
Z-PACK 2 Mm FB (Futurebus+) Receptacle And Pin Header Connectors PDF English Workmanship Specification
Ocena Wizualna Zlaczy Z-Pack Future Bus TIF Polish
Ocena Wizualna Zlaczy Z-Pack Future Bus PDF Polish Product Specification
Connector, Z-PACK*, 2 Mm FB, Signal And Power PDF English Qualification Test Report
Connector, Z-PACK, 2mm FB, Signal & Power TIF English
Connector, Z-PACK, 2mm FB, Signal & Power PDF English
Connector, Z-PACK, 2mm FB, Signal & Power PDF Japanese
FEATURES
Please review product documents or contact us for the latest agency approval information. Please Note: Use the Product Drawing for all design activity.
Product Type Features

Customer View Model

Module Type Signal
Connector Style Receptacle

Connector & Contact Terminates To Printed Circuit Board

Post Type Solder Post

Row-to-Row Spacing 2 mm [.079 in]

PCB Mounting Orientation Right Angle

Connector Type Connector Assembly

Boss Without

Product Type Connector

Configuration Features

Stackable No

Number of Positions 120

Number of Rows 5

Sequencing No

Number of Signal Positions 120

Electrical Characteristics

Dielectric Withstanding Voltage (VAC) 1000

Voltage (VAC) 30

Insulation Resistance (M Ω) 100 – 5000

Body Features

Post Plating Material Tin

Contact Features

Solder Tail Contact Plating Material Tin

Contact Configuration Dual Beam

Contact Mating Area Plating Material Gold

Contact Mating Area Plating Thickness .05 µm [1.9685 µin]

Contact Current Rating (Max) (A) 3

Solder Tail Contact Plating Thickness 3.81 µm [149.9997 µin]

Contact Layout Matrix

Contact Base Material Phosphor Bronze

Contact Type Socket

Termination Features

Termination Method to PC Board Through Hole - Solder

Termination Post Length 2.73 mm [.107 in]

Interface Type Futurebus+

Mechanical Attachment

Mating Alignment Type Polarization

PCB Mount Retention Without

PCB Mount Alignment Type Locating Posts

Housing Features

Centerline (Pitch) 2 mm [.079 in]

Housing Material LCP (Liquid Crystal Polymer)

Housing Color Natural

Dimensions Height 13.3 mm [.52269 in] **Tail Length** 2.73 mm [.107289 in] **Usage Conditions Operating Temperature Range (°C)** -55 – 125 Operation/Application **Assembly Process Feature** Board Standoff Pick and Place Cover Without Packaging Features Packaging Method Tube Packaging Quantity 12 **PRODUCT COMPLIANCE** Statement of Compliance **Statement of Compliance** PDF